

Title (en)

DEVICE FOR PARTIAL EMBOSSING OF SEALING LIDS AND METHOD FOR PARTIAL EMBOSSING OF SEALING LIDS

Title (de)

VORRICHTUNG ZUM TEILWEISEN PRÄGEN VON DECKELN UND VERFAHREN ZUM TEILWEISEN PRÄGEN VON DECKELN

Title (fr)

DISPOSITIF D'ESTAMPAGE PARTIEL D'OPERCULES ET PROCÉDÉ D'ESTAMPAGE PARTIEL D'OPERCULES

Publication

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Application

EP 15763835 A 20150908

Priority

- EP 14003089 A 20140908
- EP 2015001805 W 20150908

Abstract (en)

[origin: WO2016037697A1] The device for embossing part of an area of and punching out of sealing blanks from a film strip comprises an embossing tool and an adjacently arranged punching tool. The embossing tool in turn comprises a female and a male die (1), wherein the male die has three-dimensional elements (7) arranged in an outer area (3) and in a central area (5), and the male die and female die are pivotably mounted in a spatial position about an axis A standing substantially perpendicular in relation to the film strip. Alternatively, the female die can be exchanged for an elastic medium. The elastic medium is preferably not pivotably mounted.

IPC 8 full level

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CPC (source: EP US)

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